Infineon Technologies Bipolar
GmbH & Co. KG

Product/process change notification

PCN N° 2023-141-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Harmonization of 60mm Standard Module Housing

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2023-06-30**
- Infineon aligns with the widely recognized JEDEC STANDARD **"JESD46",** which stipulates: **"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board Dr. Wolfgang Eder
Management Board Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg
Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

Product/process change notification

PCN N° 2023-141-A

Products affected

Please refer to attached affected product list
“PCN_2023-141-A_[*customer-no*].pdf”

Detailed change information

Subject

Change of Housing concept for 60mm Modules and Chip Harmonization

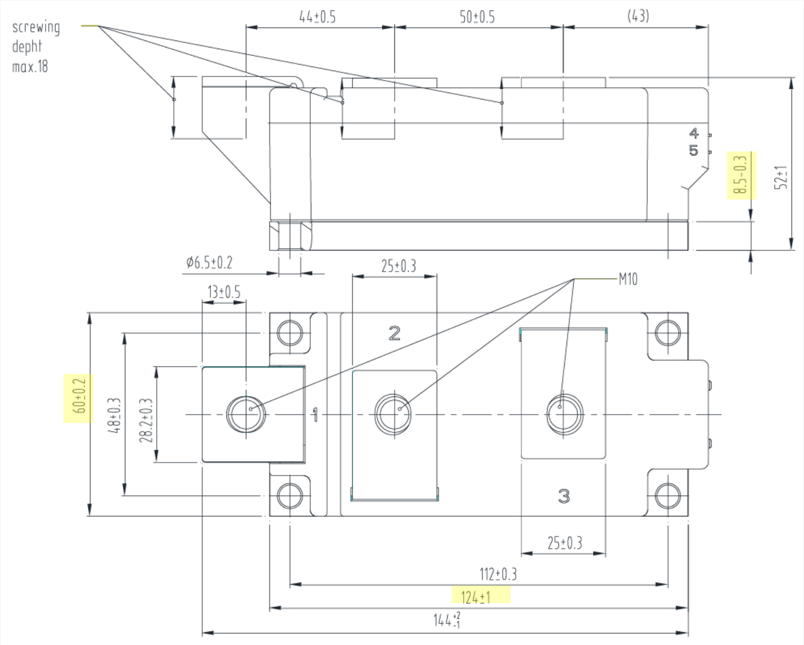
Reason

Harmonization of different Housings to a modular Package Design
In regards to delivery reliability. Harmonization of chip production

Description

Old

- Encapsulation: hard resin
- Baseplate thickness: 8.5mm
- Baseplate material: Copper
- Outer dimension of module footprint: L=124mm; W=60mm



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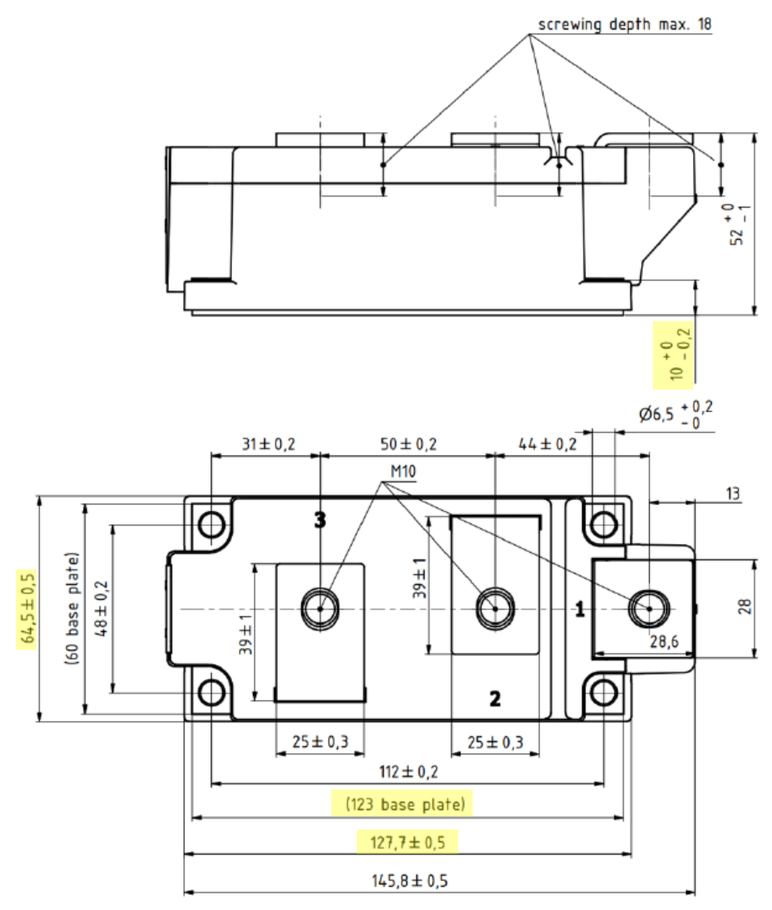
- **New**

- Encapsulation: soft gel
- Baseplate thickness: 10mm
- Baseplate material: Aluminum
- Outer dimension of module footprint: L=127,7mm; W=64,5mm



▸ Product identification

By SP Number and Datecode

▸ Impact of change

Change of external dimensions of module
No change in electrical and thermal data

▸ Attachments

“pcn_2023-141-A_[*customer-no*].pdf” affected product list

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Time schedule

Final qualification report	available
First samples available	available
Intended start of delivery	2023-09-01

If you have any questions, please do not hesitate to contact your local sales office.

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Harmonization of 60mm Standard Module Housing

Affected products sold to FUTURE ELECTRONICS INC. (4000624)

Sales name	SP number	OPN	Package	Customer part number
TT500N16KOF	SP001146866	TT500N16KOFHPSA2	BG-PB60AT-1	TT500N16KOFHPSA2

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Harmonization of 60mm Standard Module Housing

Affected products sold to FUTURE ELECTRONICS LTD. (4049887)

Sales name	SP number	OPN	Package	Customer part number
TT500N16KOF	SP001146866	TT500N16KOFHPSA2	BG-PB60AT-1	TT500N16KOFHPSA2

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Customer approval form

Harmonization of 60mm Standard Module Housing

☐ **Please list product(s) affected in your application(s):**

Please check the appropriate box below:

☐ **We agree with this proposed change and its schedule.**

☐ **We have objections:**

☐ **We need more information:**

☐ **We need samples:**

Sender

Company:	Name:
Address/location:	E-Mail:
Telephone:	
Signature	Date:

Product/process change notification

PCN N° 2023-141-A

Please return to your sales partner:

Company: Infineon Technologies AG

Name:

Address/Location :

E-mail:

Telephone: